



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Cobbley et al.

Serial No.: 10/693,286

Filed: October 23, 2003

For: METHOD FOR MANUFACTURING
FLIP-CHIP SEMICONDUCTOR
ASSEMBLY

Confirmation No.: 2348

Examiner: T. Nguyen

Group Art Unit: 2813

Attorney Docket No.: 2269-3437.7US
(97-0514.07/US)

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January 11, 2005

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

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Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.